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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/081,425	02/22/2002	Rajendra Pendse	CPAC 1011-2 US	9980
22470	7590	09/23/2003		
HAYNES BEFFEL & WOLFELD LLP P O BOX 366 HALF MOON BAY, CA 94019			EXAMINER	
			GEYER, SCOTT B	
		ART UNIT	PAPER NUMBER	
		2829		

DATE MAILED: 09/23/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary

Scott B. Geyer 2829
-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address.
Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
- Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

Disposition of Claims

4) Claim(s) 1,3-7 and 12-17 is/are pending in the application.
4a) Of the above claim(s) _____ is/are withdrawn from consideration.
5) Claim(s) _____ is/are allowed.
6) Claim(s) 1,4-7,12 and 14-17 is/are rejected.
7) Claim(s) 3 and 13 is/are objected to.
8) Claim(s) _____ are subject to restriction and/or election requirement.
Application Papers

Application Papers

9) The specification is objected to by the Examiner.

10) The drawing(s) filed on 19 May 2003 is/are: a) accepted or b) objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

11) The proposed drawing correction filed on _____ is: a) approved b) disapproved by the Examiner.
If approved, corrected drawings are required in reply to this Office action.

12) The oath or declaration is objected to by the Examiner.

Priority under 35 U.S.C. §§ 119 and 120

13) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
a) All b) Some * c) None of:
1. Certified copies of the priority documents have been received.
2. Certified copies of the priority documents have been received in Application No. ____.
3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
* See the attached detailed Office action for a list of the certified copies not received.

14) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).
a) The translation of the foreign language provisional application has been received.

15) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.

Attachment(s)

1) Notice of References Cited (PTO-892)
2) Notice of Draftsperson's Patent Drawing Review (PTO-948)
3) Information Disclosure Statement(s) (PTO-1449) Paper No(s) _____.
4) Interview Summary (PTO-413) Paper No(s). _____.
5) Notice of Informal Patent Application (PTO-152)
6) Other: _____

DETAILED ACTION

Continued Examination Under 37 CFR 1.114

A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after allowance or after an Office action under *Ex Parte Quayle*, 25 USPQ 74, 453 O.G. 213 (Comm'r Pat. 1935). Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, prosecution in this application has been reopened pursuant to 37 CFR 1.114. Applicant's submission filed on August 7, 2003 has been entered.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1, 4-7, 12 and 14-17 are rejected under 35 U.S.C. 102(b) as being anticipated by Lake (6,087,731).

As to ***claims 1, 12 and 15***, Lake teaches a method of encapsulating flip chip interconnects comprising application of a limited quantity of resin 32 (see figure 4) to the interconnect bumps 24 of a IC chip 20,22. The step of applying resin, as taught by Lake, comprises dipping the IC chip with interconnect bumps 24 into a pool of the resin

32 and then withdrawing the IC chip from the pool of resin 32. Thereafter, the IC chip device can be bonded to other substrates.

As to ***claims 4 and 14***, Lake teaches a method of encapsulating flip chip interconnects wherein the depth of the resin pool is such that the surface of the IC chip device does not touch the pool of resin.

As to ***claim 5***, Lake teaches the reservoir of resin in figures 4 and 5 wherein the reservoir has a bottom 34 and wherein the resin pool 32 has a depth. The interconnect bumps are dipped into the pool such that the bumps contact the bottom surface 34 (see figure 6), after which the bumps are withdrawn from the pool of resin.

As to ***claims 6 and 16***, Lake teaches the depth of the pool of resin 32 is approximate the standoff height (see figures 4-6).

As to ***claims 7 and 17***, Lake teaches the depth of the pool of resin 32 is less than the standoff height, such that the bottom surface of the chip does not contact the pool of resin 32 (see figures 4-6).

Allowable Subject Matter

Claims 3 and 13 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims. The prior art of record and to the examiner's knowledge does not teach or render obvious, at least to the skilled artisan, the instant invention regarding dipping an IC chip into a pool of resin where the depth of the pool of resin approximates a bump standoff height, such that when the chip with interconnects

is withdrawn from the pool of resin, a quantity of the resin remains on the chip surface as well as the chip interconnects.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Scott B. Geyer whose telephone number is (703) 306-5866. The examiner can normally be reached on weekdays, between 10:00am - 6:30pm. E-mail: scott.geyer@uspto.gov

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kamand Cuneo can be reached on (703) 308-1233. The fax phone number for the organization where this application or proceeding is assigned is (703) 872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

SBG

SBG
September 22, 2003


EVAN PERT
PRIMARY EXAMINER